RNEY)

DECLAL . COR PATENT APPLICATION (WITH POWER C.

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

m is attached beseto

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND APPARATUS FOR TRANSFER MOLDING ENCAPSULATION OF A SEMICONDUCTOR DIE WITH ATTACHED HEAT SINK, the specification of which (check one):

D was filed on as t	Inited States application serial no.	and was amended on .		
		nd was amended under PCT Article 19 on	<del></del> •	
•	and understand the contents of the above-ident	fied specification, including the claims, as amen	ded by any as	mendmen
referred to above.				
		formation known to me to be material to the pate	entability of th	ne subject
matter claimed in this application, as "	materiality* is defined in Title 37, Code of Fed	deral Regulations § 1.56.		
		a)-(d) or § 365(h) of any foreign application(s) f		
		country other than the United States of America ation page any foreign application for patent or i		
		nited States of America having a filing date before		uncate ti
pplication(s) on which priority is claim				
rior foreign/PCT application(s):		•		
	. •		Priority C	:laimed
(number)	(country)	(day/month/year filed)	Yes	No
(number)	(country)	(day/month/year filed)	Yes	No
		States application(s) or § 365(c) of PCT internat		_
(application serial no.)	(filing date)	(status - pending, patented or a	(bandoned)	
(application service)	( <b>,</b>	terming, beautiful at a		
(application serial no.)	(filing date)	(status - pending, patented or a	handoned)	
I hereby claim the benefit under Title	35, United States Code, § 119(e) of any Unite	d States provisional application(s) listed below:		
(provisional application no.)	(filing date)			
(provisional application no.)	(filing date)	<del></del>		
(provisional application no.)	(filing date)	<del></del>		
	ered Practitioners to prosecute this application	and to transact all business in the Patent and Tra	idemark Offic	:e
onnected therewith:				
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	Salt Lake City, Utah 84110			
I hereby declare that all statements ma	ade herein of my own knowledge are true and	that all statements made on information and beli	ef are helieve	d to be
ie; and further that these statements we	re made with the knowledge that willful false i	statements and the like so made are punishable h	y fine or imp	risonmen
both, under Section 1001 of Title 18 of	f the United States Code and that such willful	false statements may jeopardize the validity of the	ne application	or any

Full name of sole inventor: Richard W. Wensel Inventor's signature

Residence: Roise Idaho

Date

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